

# SN54BCT623, SN74BCT623 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS020A – SEPTEMBER 1988 – REVISED NOVEMBER 1993

- State-of-the-Art BiCMOS Design Significantly Reduces  $I_{CCZ}$
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Plastic and Ceramic 300-mil DIPs (J, N)

## description

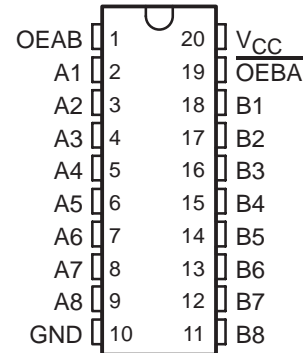
The 'BCT623 bus transceiver is designed for asynchronous communication between data buses. The control function implementation allows for maximum flexibility in timing. The 'BCT623 provides true data at its outputs.

This device allows data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the output-enable (OEAB and  $\overline{OEBA}$ ) inputs.

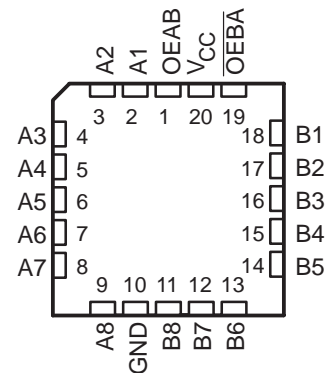
The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and  $\overline{OEBA}$ . Each output reinforces its input in this configuration. When both OEAB and  $\overline{OEBA}$  are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 in all) will remain at their last states.

The SN54BCT623 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74BCT623 is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54BCT623 . . . J OR W PACKAGE  
SN74BCT623 . . . DW OR N PACKAGE  
(TOP VIEW)



SN54BCT623 . . . FK PACKAGE  
(TOP VIEW)



FUNCTION TABLE

INPUTS		OPERATION
$\overline{OEBA}$	OEAB	
L	L	B data to A bus
L	H	B data to A bus, A data to B bus
H	L	Isolation
H	H	A data to B bus



# SN54BCT623, SN74BCT623 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54BCT623		SN74BCT623		UNIT
				MIN	TYP†	MAX	MIN	
$V_{IK}$		$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$	-1.2		-1.2		V
$V_{OH}$	A port	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -1\text{ mA}$	2.5	3.4	2.5	3.4	V
			$I_{OH} = -3\text{ mA}$	2.4	3.3	2.4	3.3	
	B port	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.3	2.4	3.3	
			$I_{OH} = -12\text{ mA}$	2	3.2			
			$I_{OH} = -15\text{ mA}$			2	3.1	
$V_{OL}$	A port	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 20\text{ mA}$	0.3	0.5			V
			$I_{OL} = 24\text{ mA}$			0.35	0.5	
	B port	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 48\text{ mA}$	0.38	0.55			
			$I_{OL} = 64\text{ mA}$			0.42	0.55	
$I_I$	A or B port	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 5.5\text{ V}$	1		1		mA
	OEAB or OEBA			0.1		0.1		
$I_{IH}^\ddagger$	A or B port	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 2.7\text{ V}$	70		70		$\mu\text{A}$
	OEAB or OEBA			20		20		
$I_{IL}^\ddagger$	A or B port	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 0.5\text{ V}$	-0.65		-0.65		mA
	OEAB or OEBA			-0.6		-0.6		
$I_{OS}^\S$	A port	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0$	-60	-150	-60	-150	mA
	B port			-100	-225	-100	-225	
$I_{CCL}$	A to B	$V_{CC} = 5.5\text{ V}$		58	92	58	92	mA
$I_{CCH}$	A to B	$V_{CC} = 5.5\text{ V}$		33	53	33	53	mA
$I_{CCZ}$		$V_{CC} = 5.5\text{ V}$		6	11	6	11	mA
$C_i$	OEAB or OEBA	$V_{CC} = 5\text{ V}$ ,	$V_I = 2.5\text{ V}$ or $0.5\text{ V}$	5		5		pF
$C_{io}$	A to B	$V_{CC} = 5\text{ V}$ ,	$V_O = 2.5\text{ V}$ or $0.5\text{ V}$	9		9		pF
	B to A			12		12		

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ For I/O ports, the parameters  $I_{IH}$  and  $I_{IL}$  include the off-state output current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.



# SN54BCT623, SN74BCT623 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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## switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, C <sub>L</sub> = 50 pF, R <sub>1</sub> = 500 Ω, R <sub>2</sub> = 500 Ω, T <sub>A</sub> = 25°C			V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>1</sub> = 500 Ω, R <sub>2</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			'BCT623			SN54BCT623		SN74BCT623		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	B	0.5	3.1	4.7	0.5	5.3	0.5	5.2	ns
t <sub>PHL</sub>			1.7	4.9	6.9	1.7	7.6	1.7	7.4	
t <sub>PLH</sub>	B	A	0.9	4.1	5.9	0.9	6.8	0.9	6.7	ns
t <sub>PHL</sub>			1.8	5.3	7.6	1.8	8.3	1.8	8	
t <sub>PZH</sub>	$\overline{\text{OEBA}}$	A	3.1	6.8	9.1	3.1	10.7	3.1	10.6	ns
t <sub>PZL</sub>			3.3	7.2	9.6	3.3	11.3	3.3	10.7	
t <sub>PHZ</sub>	$\overline{\text{OEBA}}$	A	1.9	6.1	8.3	1.9	10.6	1.9	9.8	ns
t <sub>PLZ</sub>			1.1	4.6	7	1.1	8.1	1.1	7.8	
t <sub>PZH</sub>	OEAB	B	2	5	6.8	2	7.8	2	7.6	ns
t <sub>PZL</sub>			2.7	6.2	8	2.7	9.3	2.7	8.9	
t <sub>PHZ</sub>	OEAB	B	1.1	4.6	6.5	1.1	8	1.1	7.7	ns
t <sub>PLZ</sub>			0.3	3.2	6.3	0.3	7.2	0.3	7.1	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9094001M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9094001MRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
5962-9094001MSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SN74BCT623DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT623DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT623DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT623N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74BCT623NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74BCT623NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT623NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74BCT623NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54BCT623FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54BCT623J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SNJ54BCT623W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT623NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74BCT623NSR	SO	NS	20	2000	346.0	346.0	41.0



J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

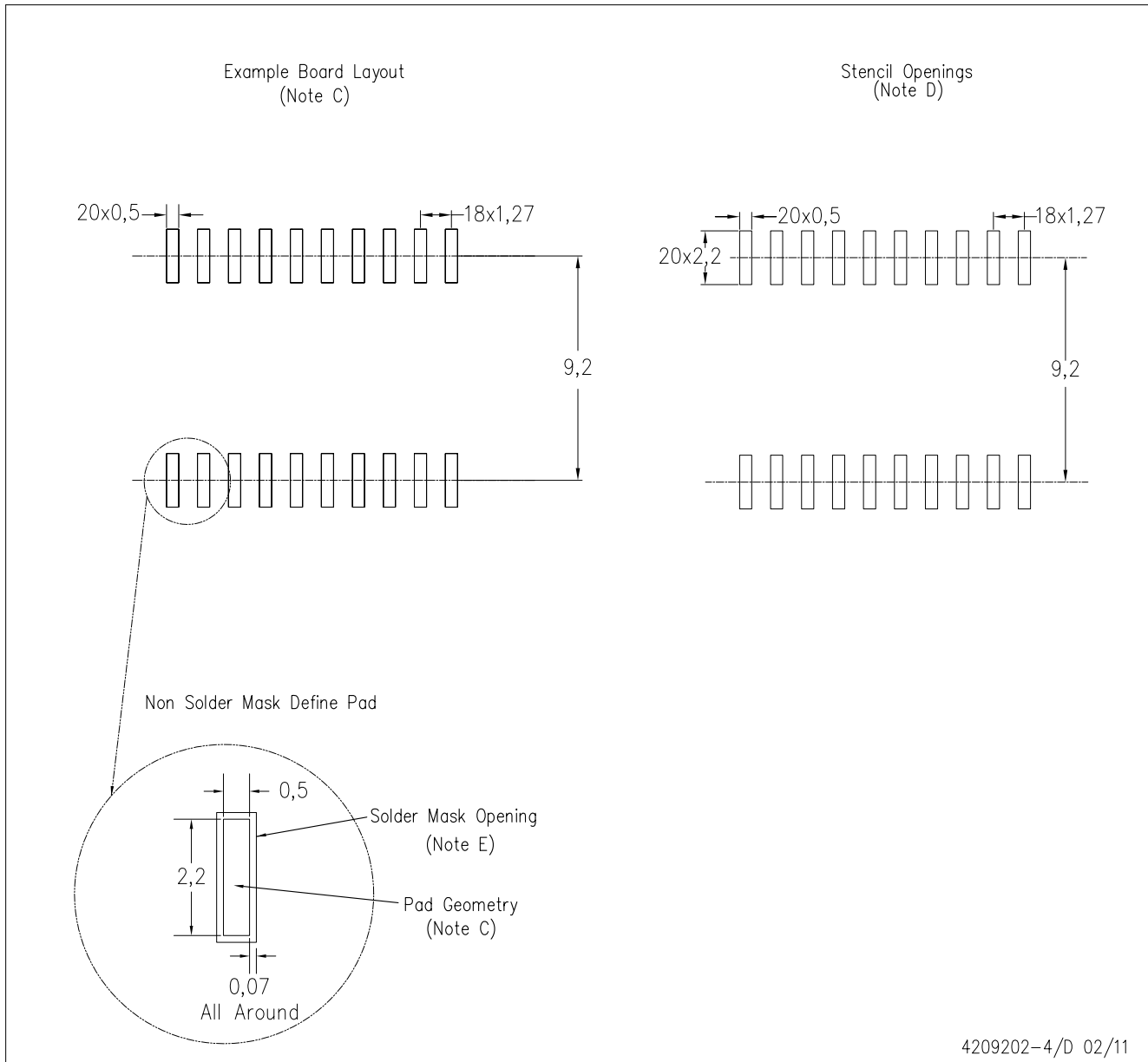
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
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